IN THE CLAIMS

Kindly amend claim 1, cancel claim 2 and add new claims 13-23, so that the claims appear as follows.

1. (Currently Amended) A water soluble protective paste for protecting metal circuits during the manufacture of electronic modules, comprising: a salt, a glycerol and a densifier dissolved in water, the salt being 5% to 110% of the glycerol by weight and the densifier being 5% to 90% of the salt by weight.

2. (Cancelled) The water soluble protective paste of claim 1 wherein the salt is 5% to 110% of the glycerol in weight and the densifier is 5% to 90% of the salt in weight.

3. (Original) The water soluble protective paste of claim 2 wherein the salt is 8% to 30% of the glycerol in weight and the densifier is 7% to 25% of the salt in weight.

4. (Original) The water soluble protective paste of claim 1 wherein the salt is Sodium citrate.

5. (Original) The water soluble protective paste of claim 1, wherein the salt is Potassium citrate.

6. (Original) The water soluble protective paste of claim 1 wherein the salt is about 25% of the glycerol in weight.

7. (Original) The water soluble protective paste of claim 6 wherein the densifier is about 20% of the salt in weight.

8. (Original) The water soluble protective paste of claim 1 wherein the densifier is a Hydrocolloid.

9. (Original) The water soluble protective paste of claim 8 wherein the Hydrocolloid is Gum Acacia.

10. (Original) A method of selectively dispensing the water soluble protective paste of claim 1 by means of offset printing.

11. (Currently Amended) A method of protecting metal circuits and pads on the surface of an electronic board during manufacturing steps, comprising:

- selectively dispensing over the metal circuits and pads the water soluble protective paste of ~~any~~ claim 1 ~~to 9~~, by means of offset printing;

- drying the dispensed layer obtaining a solid protective film.

12. (Currently Amended) A method for manufacturing a multi chip module having on the same substrate at least one wire bonded chip and at least one Surface Mount Technology (SMT) chip, the method comprising the steps of:

- protecting, with the method of claim 11, the metal circuits and pads to which the wire bonded chip will be connected;

- mounting the at least one SMT chip;

- removing the protective layer from the metal circuits and pads;

- attaching and bonding the at least one ~~Wire Bond~~ wire bonded chip.

13. (New) A water soluble protective paste for protecting metal circuits during the manufacture of electronic modules, comprising: a salt, a glycerol and a densifier dissolved in water, the salt being about 25% of the glycerol by weight.

14. (New) The water soluble protective paste of claim 13 wherein the salt is 5% to 110% of the glycerol in weight and the densifier is 5% to 90% of the salt in weight.

15. (New) The water soluble protective paste of claim 14 wherein the salt is 8% to 30% of the glycerol in weight and the densifier is 7% to 25% of the salt in weight.

16. (New) The water soluble protective paste of claim 13 wherein the salt is Sodium citrate.

17. (New) The water soluble protective paste of claim 13, wherein the salt is Potassium citrate.

18. (New) The water soluble protective paste of claim 13 wherein the densifier is about 20% of the salt in weight.

19. (New) The water soluble protective paste of claim 13 wherein the densifier is a Hydrocolloid.

20. (New) The water soluble protective paste of claim 19 wherein the Hydrocolloid is Gum Acacia.

21. (New) A method of selectively dispensing the water soluble protective paste of claim 13 by means of offset printing.

22. (New) A method of protecting metal circuits and pads on the surface of an electronic board during manufacturing steps, comprising:

- selectively dispensing over the metal circuits and pads the water soluble protective paste of claim 13, by means of offset printing;
- drying the dispensed layer obtaining a solid protective film.

23. (New) A method for manufacturing a multi chip module having on the same substrate at least one wire bonded chip and at least one Surface Mount Technology (SMT) chip, the method comprising the steps of:

- protecting, with the method of claim 22, the metal circuits and pads to which the wire bonded chip will be connected;
- mounting the at least one SMT chip;
- removing the protective layer from the metal circuits and pads;

- attaching and bonding the at least one wire bonded chip.